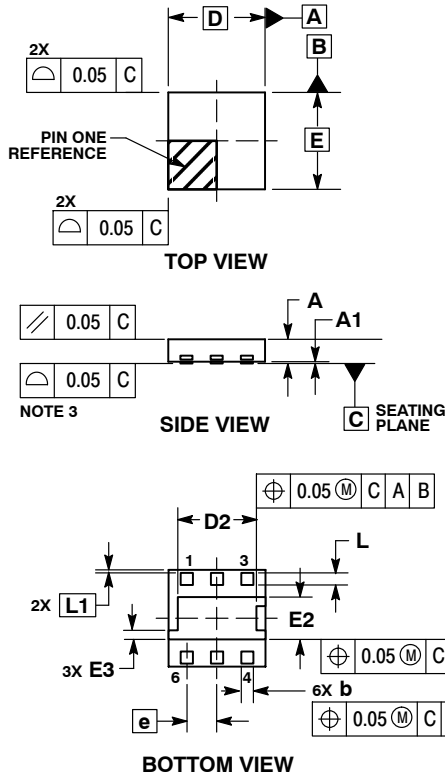


SCALE 4:1

**XDFN6 1.6x1.6, 0.5P**  
CASE 711AC  
ISSUE O

DATE 21 OCT 2010



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.60	BSC
D2	1.25	1.35
E	1.60	BSC
E2	0.65	0.75
E3	0.15	REF
e	0.50	BSC
L	0.15	0.25
L1	0.05	BSC

**GENERIC MARKING DIAGRAM\***

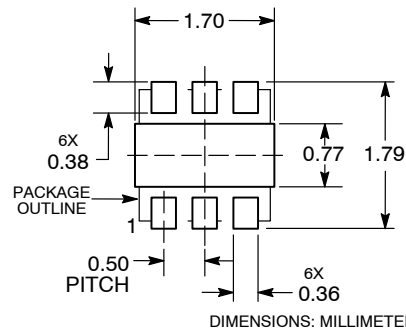

XXXX = Specific Device Code

MM = Date Code

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED MOUNTING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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